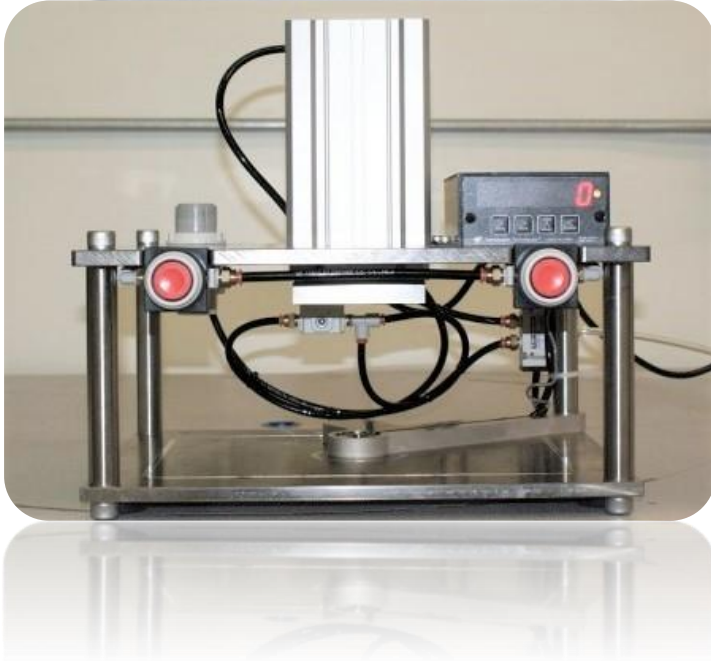


Press for Epoxy Film attachment of circuit boards
to microwave housings and baseplates

Bonding Source EFP-500E Substrate Press



- Designed specifically for pressing epoxy film adhesive and circuit boards to base plates and housings.
- Easily adjustable for various module sizes and film epoxy types.
- Multi-up and batch processing
- Provides up to 500 PSI
- Use with Bonding Source standard fixturing or use in-house designs.

TECHNICAL SPECIFICATIONS: EFP-550E EPOXY FILM PRESS

Part No.	EFP-500E
Maximum Press area	12" x 7.5"
Maximum Clearance	4.25" (Distance between press plate and base)
Maximum Pressure	500 PSI
Weight	48 lbs.
Overall Dimensions	14" W x 12"D x 13"H
House Air Requirement	80 PSI (1/4" quick connect)
Load Cell	Calibrated to 750 lbs, Unit supplied with calibrated load cell and cert.
Electrical Requirement	110V

bonding source

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